

Full Material Declaration for attached parts list

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Diotec Semiconductor AG

DUNS-Nummer: 330866844

-, Kreuzmattenstr. 4, Heitersheim, B.-W., 79423, Germany

Declarations Autorisiert durch:

Udo Steinebrunner, Product Manager, -

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Materialien und Stoffe

Verwendung/Andordnung	Material group	% w/w des Materials im Artikel	Substances in the material	CAS Number	% w/w des Stoffs im Artikel
Chip (die)	Other inorganic materials	0.30000%	Nickel	7440-02-0	1.50000%
			Silicon dioxide	14808-60-7	5.05000%
			Silicon	7440-21-3	93.45000%
Die attach	Lead and Lead alloys	0.10000%	Silver	7440-22-4	1.50000%
			Tin	7440-31-5	3.00000%
			Lead	7439-92-1	95.50000%
Encapsulation	EP (Epoxy resin)	62.40000%	1,3-Isobenzofurandione, hexahydro-5-methyl-	19438-60-9	0.10000%
			Carbon black	1333-86-4	1.25000%
			P 33 (carbon black)	1333-86-4	2.00000%
			Benzyl-N,N-dimethylamine	103-83-3	3.10000%
			1,3- Isobenzofurandione, 3a,4,7,7a- tetrahydro- 4- methyl-	5333-84-6	6.00000%
			cis-1,2,3,6- Tetrahydrophthalic anhydride	85-43-8	9.25000%
			1,3-Isobenzofurandione, tetrahydro-5-methyl-	34090-76-1	10.65000%
			7- Oxabicyclo[4.1.0]heptane-3- carboxylic acid, 7- oxabicyclo[4.1.0]hept- 3- ylmethyl ester	2386-87-0	12.65000%
			Silica	14808-60-7	55.00000%

Leadfinish	Tin plating	2.70000%	Tin	7440-31-5	100.00000%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	10.40000%	Copper	7440-50-8	100.00000%
Screws	Copper alloys	24.10000%	iron	14127-53-8	1.95000%
			Lead	7439-92-1	2.60000%
			Zinc	7440-66-6	37.67000%
			Copper	7440-50-8	57.78000%

Beigefügte Artikelliste

Part number	Artikelbezeichnung	Artikelmasse	Artikelmasse UoM
SI-Exxxx	Diode Module (Cylinder)	600	g

Based on the information currently available, these substances do not pose any risk if the articles are used as intended (including disposal). Additional information is not necessary to allow safe use of the article.